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## Chapter 1. Introduction

The growing popularity of standard USB PD3.1 chargers for mobile phones and notebook PCs spurs the demand for leveraging standard PD3.1 chargers to replace purposely and individually built chargers for battery-power electronic devices to reduce E-Waste.

The AP33772S Evaluation Board (EVB) is intended to be used as an evaluation vehicle for charging applications between a Type C Connector-equipped Device (**TCD**, Energy Sink) and a Type C Connector-equipped PD3.1 compliance Charger or Adaptor (**PDC**, Energy Source).

Figure 1 illustrates a TCD, embedded with a PD3.1 Sink controller IC (AP33772S). This is physically connected to a PDC, embedded with a USB PD3.1 decoder (AP43771) through a Type-C to Type-C cable. Based on the built-in USB PD3.1 compliant firmware, the AP33772S and AP43771 pair can go through the USB PD3.1 standard attachment procedure to establish a suitable PD3.1 charging state.

The AP33772S Evaluation Board (EVB) User Guide explains a flexible I2C setting arrangement (I2C Interface Pin, I2C Register Map, and Operations) to request the desired input voltage and input power for a typical TCD. Various system protection functions and system status checks can also be performed by accessing the relevant I2C register contents by the TCD's host MCU device.

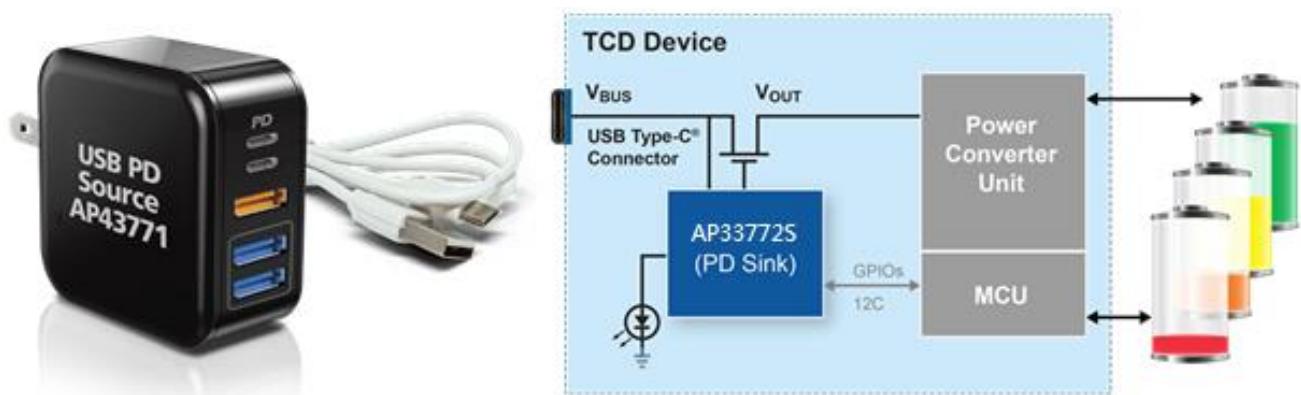


Figure 1 – A typical TCD uses the AP33772S PD Sink Controller with I2C Interface to request power from a USB Type-C PD3.1/PPS Compliance Source Adaptor

## Chapter 2. AP33772S Sink Controller

### 2.1 Package Outline

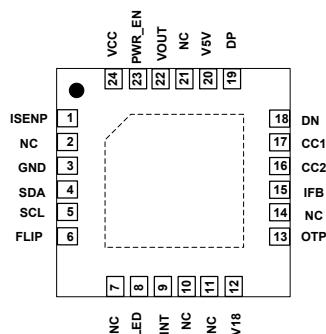


Figure 2 – AP33772S Package Outline

### 2.2 Pin Descriptions

Pin No	Pin Name	Type (Notes)	Pin Function
1	ISENP	AHV	Current Sense Positive Node, connect to the positive node of the external current sensing resistor
2	NC	-	No Connection
3	GND	GND	Ground
4	SDA	DIO	I2C Data, need to be pulled up externally
5	SCL	DI	I2C Clock, need to be pulled up externally
6	FLIP	DO	Flip indicator of Type-C plug. LOW: CC1 detected; HIGH: CC2 detected
7	NC	-	No Connection
8	LED	DO	LED Indicator Pin, refer to Table 13 for detailed description
9	INT	DO	Interrupt pin is used to inform external MCU. LOW: normal; HIGH: interrupt occurred
10	NC	-	No Connection
11	NC	-	No Connection
12	V18	DP	1.8V LDO output for internal use only. Connect a 100nF cap to GND. This pin cannot drive external load.
13	OTP	AIO	100uA Current Source output for NTC connected to ground; this NTC is used to monitor temperature variation
14	NC	-	No Connection
15	IFB	AI	For current measurement, a 100nF cap to Ground is suggested
16	CC2	AIO	Type-C Configuration Channel 2 (CC2); the CC2 pin detects, configures, and manages the connections across a USB Type-C cable
17	CC1	AIO	Type-C Configuration Channel 1 (CC1); the CC1 pin detects, configures, and manages the connections across a USB Type-C cable
18	DN	AIO	DN of Type-C Connector
19	DP	AIO	DP of Type-C Connector
20	V5V	AP	Output of the internal LDO with VCC as input; a 1μF cap is required to connect this pin to GND. When VCC is off, V5V pin can be an alternative power path for the AP33772S when provided with a 5V external power.
21	NC	-	No Connection
22	VOUT	AHV	Terminal for VOUT monitoring
23	PWR_EN	AHV	NMOS Switch gate control to switch the NMOS on or off
24	VCC	AHV	The power supply of the IC; a 1μF cap is required to connect this pin to GND pin
-	EPAD	GND	Exposed pad is suggested to connect to Ground for improved thermal dissipation

Table 1 – Pin Descriptions of the AP33772S PD Sink Controller

Notes:

- AHV – Analog High Voltage pin
- AP – Power for Analog Circuit and Analog I/O pins, 5.0V operation
- AI – Analog Input pin
- DP – Power for Digital Circuit operation
- AIO – Analog I/O pin with 5.0V operation; CC1/CC2 pins are 3.3V operation
- DIO – Digital I/O pin; all are 5.0V operation
- DI – Digital input pin; all are 5.0V operation
- DO – Digital output pin; all are 5.0V operation

## Chapter 3. EVB Hardware Details

### 3.1 EVB TOP View

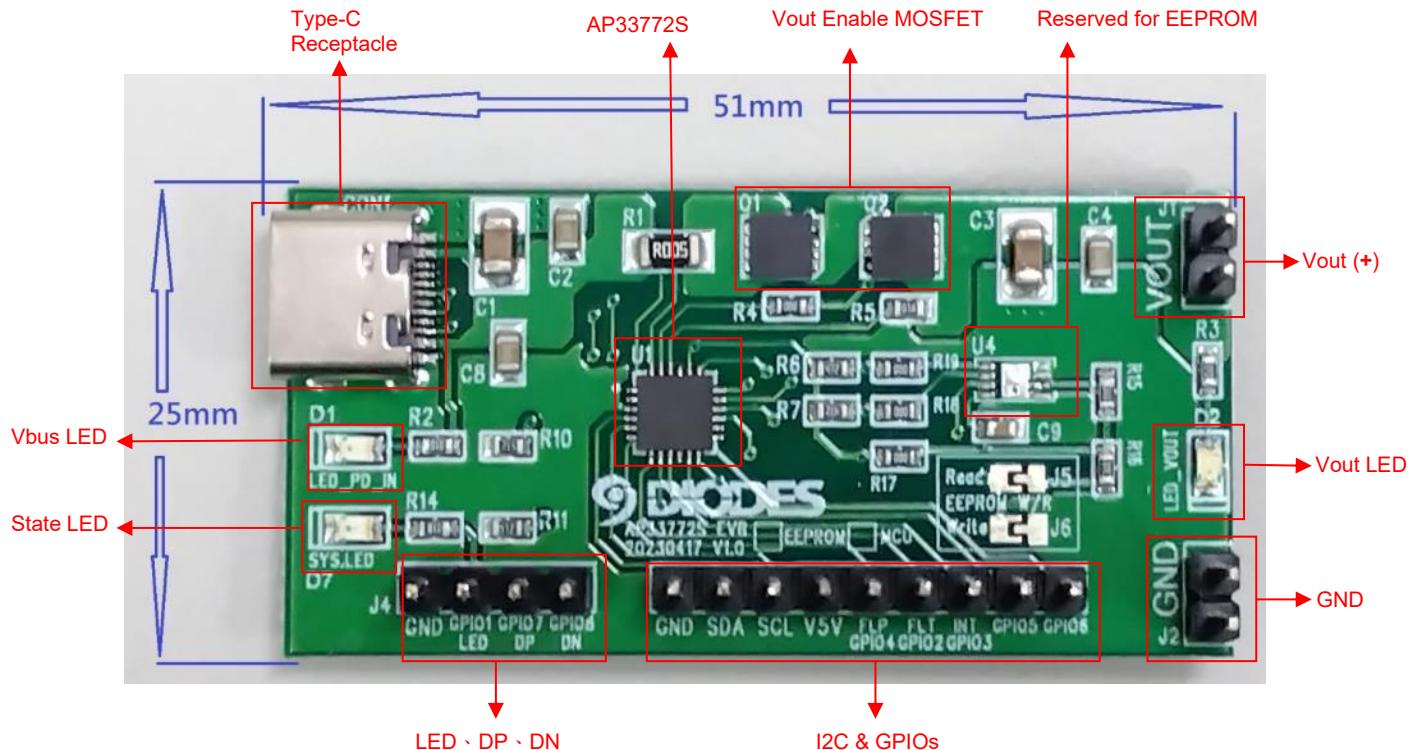


Figure 3 – AP33772S Evaluation Board top view and its key portions

### 3.2 EVB Block Diagram

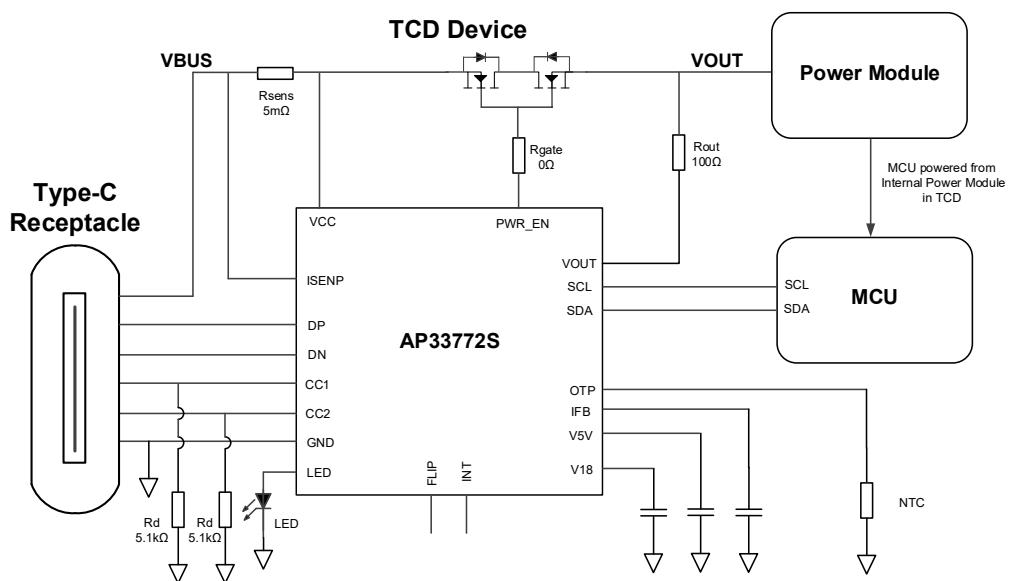


Figure 4 – AP33772S Evaluation Board Block Diagram

### 3.3 EVB Schematics

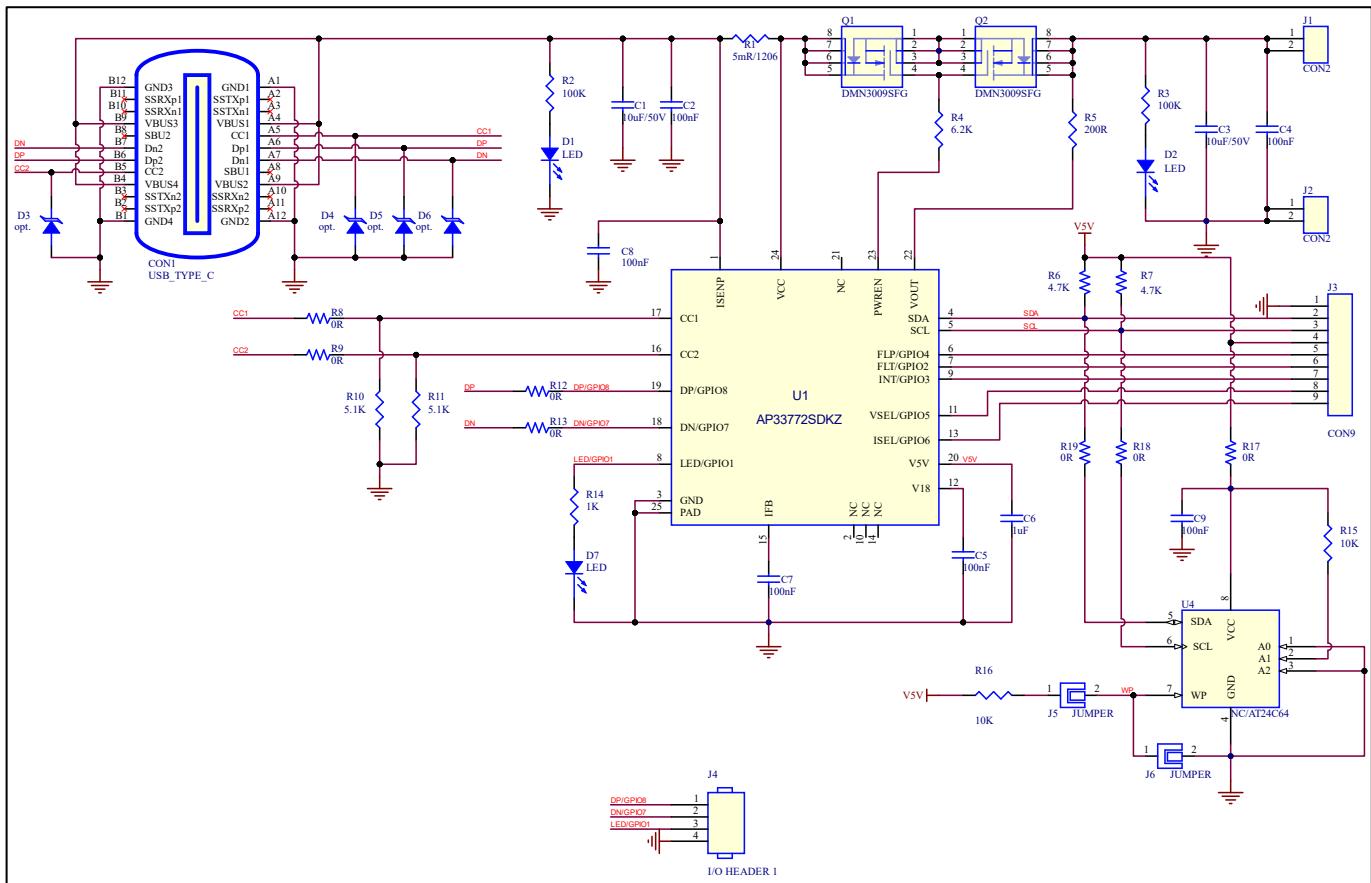


Figure 5 –Schematic of the AP33772S Evaluation Board

### 3.4 Board Outline

The AP33772S EVB outline and floor plan are shown in Figure 6, and the connector and jumper location are listed in Table 2.

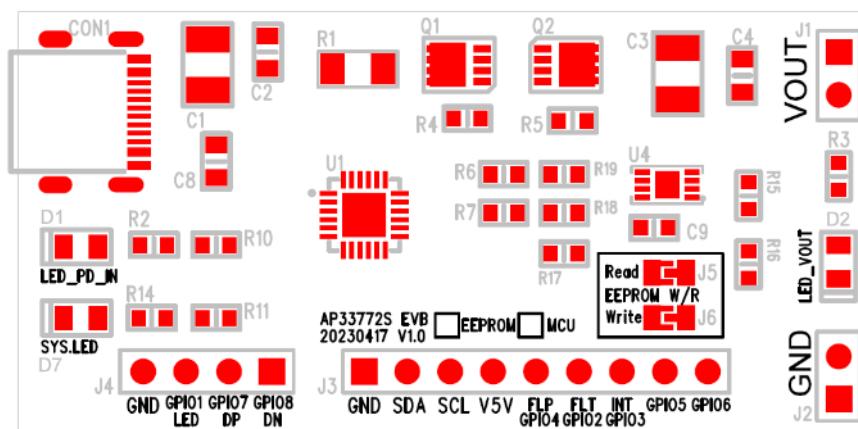


Figure 6 – Connector and jumper locations

Location	Function
J1, J2	VOUT and Load Connector
J3	I <sup>2</sup> C Bus & other test pins
J4	DP, DN & other test pins

Table 2 – Jumpers and functions of the Evaluation Board

### 3.5 EVB System BOM

Item	Quantity	Reference	Description	Manufacturer Part Number	Manufacturer
1	2	C1, C3	10 $\mu$ /50V	-	-
2	6	C2, C4, C5, C7, C8, C9	0.1 $\mu$ /50V	-	-
3	1	C6	1 $\mu$ /50V	-	-
4	7	R8, R9, R12, R13, R17, R18, R19	0R	-	-
5	1	R4	6.2K		
6	1	R5	200R	-	-
7	1	R14	1K	-	-
8	2	R6, R7	4.7K	-	-
9	2	R10, R11	5.1K	-	-
10	2	R15, R16	10K	-	-
11	2	R2, R3	100K	-	-
12	1	R1	5mR/1W 1206	SMD12A1FR005T	SART Inc.
13	3	D1, D2, D7	LED	-	-
14	2	Q1, Q2	30V/45A/4.4m $\Omega$ N-CH PowerDI3333-8	DMN3009SFG	Diodes Incorporated
15	1	U1	USB PD3.1 Sink Controller With I <sup>2</sup> C	AP33772S QFN-24	Diodes Incorporated
16	1	U4	Reserved EEPROM solder location	N/A	N/A
17	1	CON1	USB Type-C Receptacle	-	-
18	2	J1, J2	VOUT & GND	-	-
19	2	J3, J4	DP, DN, I <sup>2</sup> C, & other test pins	-	-
20	4	D3~D6	Zener Diode (option)	N/A	N/A

Table 3 – BOM list of the AP33772S EVB's schematics

## Chapter 4. EVB Quick Setup and Function Description

The AP33772S EVB provides users a convenient and flexible way to use power profile settings, as well as various status monitoring functions by the host MCU in the TCD through simple I2C interface pins (SCL and SDA).

### 4.1 Quick Setup Guide

Hardware setup steps are shown in Figure 7.

Step1: Connect a Host System (using Arduino UNO for example) to the AP33772S EVB with the below pins.

Arduino uno board	↔	AP33772S EVB
GPIO 13 pin	↔	GPIO 03 pin
I <sup>2</sup> C pin (SDA, SCL)	↔	I <sup>2</sup> C pin (SDA, SCL)
GND pin	↔	GND pin

Step 2: Connect the AP33772S EVB to a USB PD adaptor with a Type-C cable, and power on the AP33772S EVB.

Step 3: Connect the Arduino UNO board to a PC/NB with a Type-B cable, and power on the Arduino UNO board.

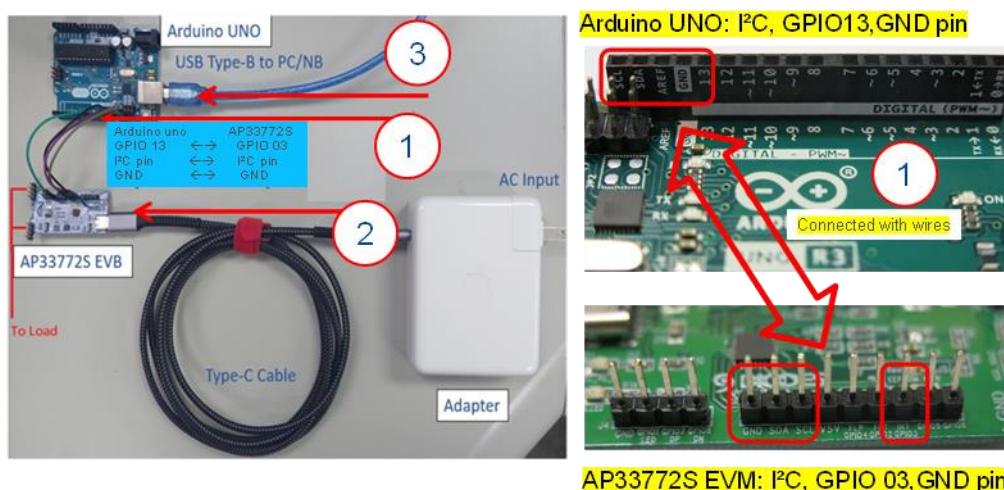
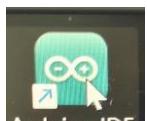


Figure 7 – AP33772S EVB Hardware Setup sequence

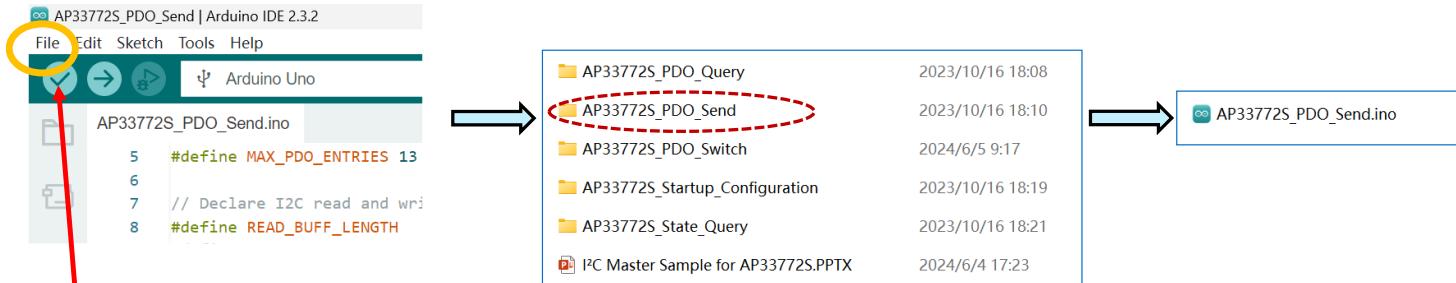
When using a Host System (single board computer or MCU-based system) with I2C interface pins (SDA, SCL) to connect to the AP33772S EVB, please make sure to power the AP33772S EVB board first before applying power to the Host System. The AP33772S EVB's power-sequencing requirement (being powered up first) is necessary due to the I2C design for the SDA and SCL pins.



## Step 1: Startup the GUI

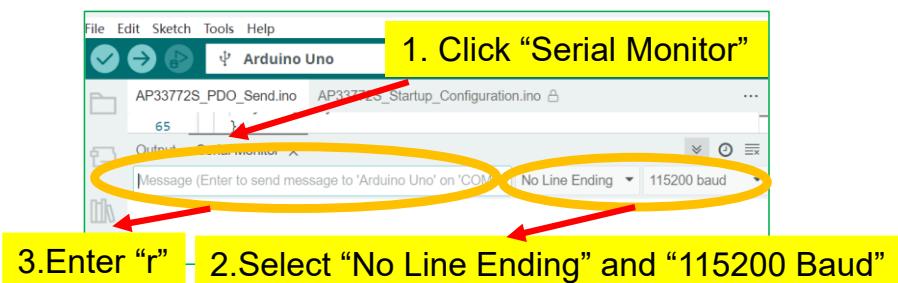
Arduino IDE

double-click the icon of Arduino on computer's desktop



Click "File" -> click "Open" -> click fold "AP33772S PDO\_Send" -> select file "AP33772S PDO\_Send.ino"

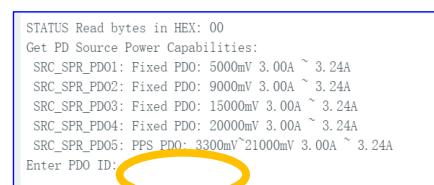
## Step 2: load the AP33772S PDO file



3. Enter "r"

2. Select "No Line Ending" and "115200 Baud"

## Step 3



After Entering "r", PD Source Power Capabilities can be selected as above, if you want to choose PDO : 20000mV/3.00A~3.24A, You only need to Enter PDO ID "4"

## Step 4: select PDO



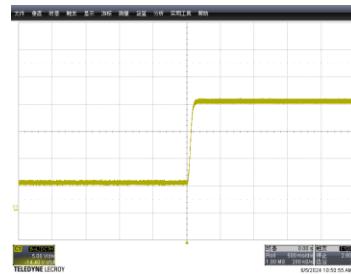
PDO is fixed, then you need to choose output current. If you need a 2.25A current, you can Enter "5". When you complete the confirmation of operating voltage and current, system output will become your target.

Step 5: select current

```
Enter PDO ID:
You entered PDO ID: 4
Operating Current Select:
0: 1.00A
1: 1.25A
2: 1.50A
3: 1.75A
4: 2.00A
5: 2.25A
6: 2.50A
7: 2.75A
8: 3.00A
9: 3.25A
10: 3.50A
11: 3.75A
12: 4.00A
13: 4.25A
14: 4.50A
15: 5.00A
```



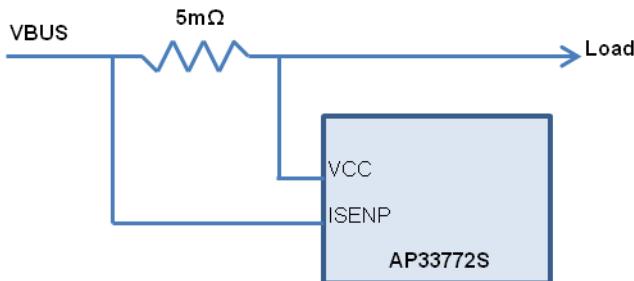
```
You entered PDO ID: 4
Operating Current Select:
0: 1.00A
1: 1.25A
2: 1.50A
3: 1.75A
4: 2.00A
5: 2.25A
6: 2.50A
7: 2.75A
8: 3.00A
9: 3.25A
10: 3.50A
11: 3.75A
12: 4.00A
13: 4.25A
14: 4.50A
15: 5.00A
You entered current: 5
I2C_SFR_PDO4 : status=0x02 RESPONSE=Success V=19920mV I=48mA T=0° C
```



Step 6: output successfully

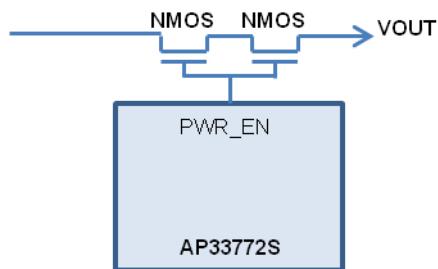
### 4.2 Application Circuit Description

#### Sensing of Input Current



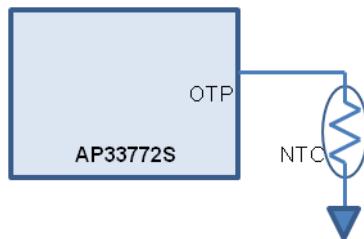
As shown in the figure above, the sense resistor is connected in series to detect the charging current. The ISENP pin is connected to the input side of the sense resistor, and the VCC pin is connected to the other side. The AP33772S detects the current by measuring the voltage drop across the current sense resistor.

#### Use of Back-to-Back N-MOS Chips



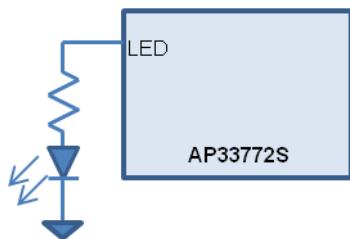
The common-source back-to-back N-MOSFET in the battery-pack protection-circuit module controls charging and plays a protective role in the occurrence of failures that may damage electrical appliances, such as overvoltage, overcurrent, and overtemperature. The back-to-back N-MOSFET control is also used to prevent backward current flows through the system when unplugging the cable from the PD charger.

#### Temperature-Sensing Circuitry



A 10k $\Omega$  NTC (negative temperature coefficient) thermistor is connected to the OTP pin and grounded nearby the potential hot spot. The characteristic data of the NTC thermistor's temperature and resistance values need to be set by the user through I2C. Then the host MCU can read and calculate the temperature and enable OTP (overtemperature protection) and de-rating functions through the I2C interface.

## LED Light Indication Circuitry



The LED light and resistor are used to connect the LED pin and ground. The LED charging indication light starts to breathe at a speed matching the battery's quick-charging pace.

## I2C Support

The AP33772S's supports I2C Interface and is used to communicate with the TCD's host MCU. The I2C pins are listed below in Table 4 and are used to set the AP33772S's register data such as Initialization, PDO, APDO, OCP, OTP, temperature, de-rating, interrupt, and so on. The AP33772S's operating status can also be monitored at the same time.

Meanwhile, INT is used as a fault-report channel to the Interrupt input pin of the host MCU, in case of any fault occurrence requiring immediate action from the host MCU.

For the I2C commands and registers, please refer to Chapter 5.

Pin No.	Pin Name	Pin Function
4	SDA	I2C Data
5	SCL	I2C Clock
9	INT	Issue an interrupt to the host MCU

Table 4 – I2C interface pin list

## Chapter 5. I2C Command/Register Summary

As an I2C slave device, the AP33772S's physical address is 0x52. All AP33772S I2C-related control operations and commands are summarized in this chapter.

### 5.1 I2C Command Format

#### Device Address Format

Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
DevAddr6	DevAddr5	DevAddr4	DevAddr3	DevAddr2	DevAddr1	DevAddr0	R/W
1	0	1	0	0	1	0	1/0

#### Command Format

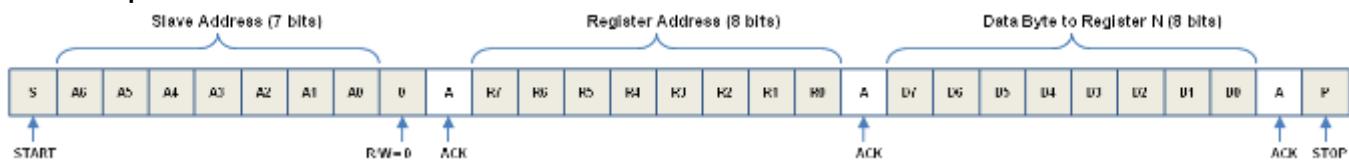
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
CmdBit7	CmdBit6	CmdBit5	CmdBit4	CmdBit3	CmdBit2	CmdBit1	CmdBit0

#### Data Format

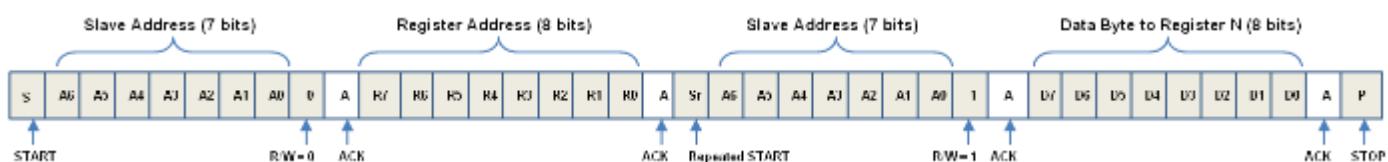
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
DataBit7	DataBit6	DataBit5	DataBit4	DataBit3	DataBit2	DataBit1	DataBit0

## 5.2 I2C Operation

### I2C Write Operation



### I2C Read Operation



## 5.3 Register Summary

The memory representation of multibyte data types on the AP33772S is in a little-endian byte order: the least significant byte (the "little end") of the data is placed at the byte with the lowest address.

Suppose the integer is stored as 4 bytes, then a variable X with a value of 0x12345678 will be stored as the following.



Register	Command	Length	Attribute	Pwr-on	Description
STATUS	0x01	1	RC	00h	Status
MASK	0x02	1	RW	03h	Interrupt enable mask
OPMODE	0x03	1	RO	00h	Operation mode
CONFIG	0x04	1	RW	F8h	System configuration options
PDCONFIG	0x05	1	RW	03h	PD mode configuration options
SYSTEM	0x06	1	RO/RW	10h	System control and information
TR25	0x0C	2	RW	2710h	Thermal Resistance @25°C, Unit: Ω
TR50	0x0D	2	RW	1041h	Thermal Resistance @50°C, Unit: Ω
TR75	0x0E	2	RW	0788h	Thermal Resistance @75°C, Unit: Ω
TR100	0x0F	2	RW	03CEh	Thermal Resistance @100°C, Unit: Ω
VOLTAGE	0x11	2	RO	0000h	The VOUT Voltage, LSB 80mV
CURRENT	0x12	1	RO	00h	The VOUT Current, LSB 24mA
TEMP	0x13	1	RO	19h	Temperature, Unit: °C The default value is 19h (25°C).
VREQ	0x14	2	RO	0000h	The latest requested voltage negotiated with the source, LSB 50mV
IREQ	0x15	2	RO	0000h	The latest requested current negotiated with the source, LSB 10mA
VSELMIN	0x16	1	RW	19h	The Minimum Selection Voltage, LSB 200mV The default value is 19h (5000mV).
UVPTHR	0x17	1	RW	01h	UVP Threshold, percentage(%) of VREQ The default value is 01h (80%).
OVPTHR	0x18	1	RW	19h	OVP Threshold, offset from VREQ. LSB 80mV The default value is 19h (2000mV).
OCPTHR	0x19	1	RW	00h	OCP Threshold, LSB 50mA
OTPTHR	0x1A	1	RW	78h	OTP Threshold, Unit: °C The default value is 78h (120°C).
DRTHR	0x1B	1	RW	78h	De-Rating Threshold, Unit: °C The default value is 78h (120°C).
SRCPDO	0x20	26	RO	All 00h	Get all PD Source Power Capabilities (SRC_SPR_PDO1 ~ SRC_EPR_PDO13)
SRC_SPR_PDO1	0x21	2	RO	0000h	Source SPR PDO1
SRC_SPR_PDO2	0x22	2	RO	0000h	Source SPR PDO2
SRC_SPR_PDO3	0x23	2	RO	0000h	Source SPR PDO3
SRC_SPR_PDO4	0x24	2	RO	0000h	Source SPR PDO4
SRC_SPR_PDO5	0x25	2	RO	0000h	Source SPR PDO5
SRC_SPR_PDO6	0x26	2	RO	0000h	Source SPR PDO6
SRC_SPR_PDO7	0x27	2	RO	0000h	Source SPR PDO7
SRC_EPR_PDO8	0x28	2	RO	0000h	Source EPR PDO8
SRC_EPR_PDO9	0x29	2	RO	0000h	Source EPR PDO9
SRC_EPR_PDO10	0x2A	2	RO	0000h	Source EPR PDO10
SRC_EPR_PDO11	0x2B	2	RO	0000h	Source EPR PDO11
SRC_EPR_PDO12	0x2C	2	RO	0000h	Source EPR PDO12
SRC_EPR_PDO13	0x2D	2	RO	0000h	Source EPR PDO13
PD_REQMSG	0x31	2	WO	0000h	Send request message with selected voltage, current and PDO index
PD_CMDSMSG	0x32	1	WO	00h	Send specific PD command message
PD_MSGRLT	0x33	1	RO	00h	Result and status of PD request or command message

Table 5 – AP33772S Register Summary

Attribute Convention

RW: Readable / Writable  
RO: Read-Only  
RC: Read-Clear  
WO: Write-Only

### 5.4 Register Description

#### STATUS

The host MCU, working as an I2C master, can access the status of the AP33772S through the STATUS register. The STATUS register will be reset to 0 after a read operation.

STATUS	Bit	Attribute	Pwr-on	Description
-	7	RC	0h	Reserved
OTP	6	RC	0h	1: OTP status
OCP	5	RC	0h	1: OCP status
OVP	4	RC	0h	1: OVP status
UVP	3	RC	0h	1: UVP status
NEW PDO	2	RC	0h	1: New source PDOs received (Valid when PDMOD = 1)
READY	1	RC	0h	1: Ready to receive I2C request/command
STARTED	0	RC	0h	1: System started. Allow system configuration (register) to be updated within 100ms.

#### MASK

The AP33772S supports a level-triggered interrupt signal through the INT pin to the host MCU. The MASK register defines the enable and disable of ON and OFF for various STATUS-defined events.

MASK	Bit	Attribute	Pwr-on	Description
-	7	RW	0h	Reserved
OTP_MSK	6	RW	0h	1: OTP status mask
OCP_MSK	5	RW	0h	1: OCP status mask
OVP_MSK	4	RW	0h	1: OVP status mask
UVP_MSK	3	RW	0h	1: UVP status mask
NEW PDO_MSK	2	RW	0h	1: NEW PDO status mask
READY_MSK	1	RW	1h	1: READY status mask
STARTED_MSK	0	RW	1h	1: STARTED status mask

#### OPMODE

The OPMODE register is defined as the AP33772S's operation mode.

When CCFLIP = 1, the CC2 is connected to the CC line.

When DR = 1, the AP33772S works in de-rating (DR) mode.

When PDMOD = 1, the AP33772S works in PD mode.

When LGCYMOD = 1, the AP33772S works in Legacy mode (non-PD).

OPMODE	Bit	Attribute	Pwr-on	Description
CCFLIP	7	RO	0h	0: CC1 is connected to CC line or unattached mode 1: CC2 is connected to CC line
DR	6	RO	0h	0: Normal mode 1: DR (de-rating) mode
-	5	RO	0h	Reserved
-	4	RO	0h	Reserved
-	3	RO	0h	Reserved
-	2	RO	0h	Reserved
PDMOD	1	RO	0h	1: PD source connected
LGCYMOD	0	RO	0h	1: Legacy source connected (non-PD)

## CONFIG

The CONFIG register is defined as the system configuration options that enable specific modules.

CONFIG	Bit	Attribute	Pwr-on	Description
DR_EN	7	RW	1h	0/1: Disable/enable DR function
OTP_EN	6	RW	1h	0/1: Disable/enable OTP function
OCP_EN	5	RW	1h	0/1: Disable/enable OCP function
OVP_EN	4	RW	1h	0/1: Disable/enable OVP function
UVP_EN	3	RW	1h	0/1: Disable/enable UVP function
-	2	RW	0h	Reserved
-	1	RW	0h	Reserved
-	0	RW	0h	Reserved

## PDCONFIG

The PDCONFIG register is defined as the PD mode configuration options that enable specific modules.

PDCONFIG	Bit	Attribute	Pwr-on	Description
-	7:4	RW	0h	Reserved
-	3	RW	0h	Reserved
-	2	RW	0h	Reserved
PPS_AV_S_EN	1	RW	1h	0/1: Disable/Enable sink PPS and AVS capability
EPR_MODE_EN	0	RW	1h	0/1: Disable/Enable EPR mode

## SYSTEM

The SYSTEM register is defined as the system information and control options that request specific functions.

By default, the VOUT MOS switches are controlled by the AP33772S. Writing the VOUTCTL parameter can force the VOUT MOS switches to turn OFF/ON.

SYSTEM	Bit	Attribute	Pwr-on	Description
-	7	RO	0h	Reserved
-	6	RO	0h	Reserved
CMDVER	5:4	RO	1h	I2C Command Version 1: Version 1.0 others: Reserved, shall not be used
-	3	RW	0h	Reserved
-	2	RW	0h	Reserved
VOUTCTL	1:0	RW	0h	VOUT control option switch 0: Auto VOUT Control (controlled by the AP33772S) 1: VOUT force OFF 2: VOUT force ON 3: Reserved, shall not be used

## TR25

The TR25 register is defined as the resistance value of the NTC thermistor at 25°C (unit: Ω).

TR25	Bit	Attribute	Pwr-on	Description
TR25	15:0	RW	2710h	The resistance value of the NTC thermistor at 25°C (unit: Ω) The default value is 2710h (10000Ω)

## TR50

The TR50 register is defined as the resistance value of the NTC thermistor at 50°C (unit: Ω).

TR50	Bit	Attribute	Pwr-on	Description
TR50	15:0	RW	1041h	The resistance value of the NTC thermistor at 50°C (unit: Ω) The default value is 1041h (4161Ω)

## TR75

The TR75 register is defined as the resistance value of the NTC thermistor at 75°C (unit: Ω).

TR75	Bit	Attribute	Pwr-on	Description
TR75	15:0	RW	0788h	The resistance value of the NTC thermistor at 75°C (unit: Ω) The default value is 0788h (1928Ω)

## TR100

The TR100 register is defined as the resistance value of the NTC thermistor at 100°C (unit: Ω).

TR100	Bit	Attribute	Pwr-on	Description
TR100	15:0	RW	03CEh	The resistance value of the NTC thermistor at 100°C (unit: Ω) The default value is 03CEh (974Ω)

## VOLTAGE

The VOLTAGE register is defined as the voltage of VOUT. The LSB (least significant bit) is 80mV.

VOLTAGE	Bit	Attribute	Pwr-on	Description
VOLTAGE	15:0	RO	0000h	The VOUT voltage; LSB is 80mV

## CURRENT

The CURRENT register is defined as the current of VOUT. The LSB is 24mA.

CURRENT	Bit	Attribute	Pwr-on	Description
CURRENT	7:0	RO	00h	The VOUT current; LSB is 24mA

## TEMP

The TEMP register is defined as the temperature near the NTC thermistor. The unit is °C. The default value is 19h (25°C).

TEMP	Bit	Attribute	Pwr-on	Description
TEMP	7:0	RO	19h	Temperature near the NTC thermistor (unit: °C) The default value is 19h (25°C)

## VREQ

The VREQ register is defined as the latest request voltage, which depends on the PD negotiation result after setting the request message (PD\_REQMSG). The LSB is 50mV.

The Host MCU writes PD\_REQMSG and will initiate a PD negotiation process. If negotiation is successful (PD\_MSGRLT.RESPONSE = 1), VREQ will be updated to the requested voltage (PD\_REQMSG.VOLTAGE\_SEL). If negotiation is unsuccessful, VREQ will not be updated.

VREQ	Bit	Attribute	Pwr-on	Description
VREQ	15:0	RO	0000h	The latest requested voltage; LSB 50mV The value depends on the PD negotiation result after setting PD_REQMSG (VOLTAGE_SEL).

## IREQ

The IREQ register is defined as the latest request current, which depends on the PD negotiation result after setting the request message (PD\_REQMSG). The LSB is 10mA.

If negotiation is successful (PD\_MSGRLT.RESPONSE=1), IREQ will be updated to the requested current (PD\_REQMSG.CURRENT\_SEL). If negotiation is unsuccessful, IREQ will not be updated.

IREQ	Bit	Attribute	Pwr-on	Description
IREQ	15:0	RO	0000h	The latest requested current; LSB 10mA The value depends on the PD negotiation result after setting PD_REQMSG (CURRENT_SEL).

## VSELMIN

The VSELMIN register is defined as the Minimum Selection Voltage. If the VREQ voltage is more than or equal to the VSELMIN voltage, the VOUT MOS switches turn ON after the system is ready (STATUS.READY = 1). The default value for VSELMIN is 19h (5000mV) and the LSB is 200mV.

VSELMIN	Bit	Attribute	Pwr-on	Description
VSELMIN	7:0	RW	19h	The Minimum Selection Voltage; the LSB is 200mV. If $V_{VREQ} \geq V_{VSELMIN}$ , VOUT MOS switches turn on after system is ready (READY=1). The default value is 19h (5000mV).

## UVPTHR

The UVPTHR register is defined as the UVP Threshold Voltage that triggers UVP protection function. The UVP Threshold Voltage is the UVPTHR percentage (%) of the VREQ voltage. The default value for the UVPTHR is 01h (80%). Please refer to the “Undervoltage Protection” section for more details.

UVPTHR	Bit	Attribute	Pwr-on	Description
-	7:4	RW	0h	Reserved
UVPTHR	3:0	RW	1h	The UVP Threshold Voltage is UVPTHR percentage (%) of VREQ voltage (unit: %) 1: 80% 2: 75% 3: 70% Others: Reserved, shall not be used The default value is 01h (80%).

## OVPTHR

The OVPTHR register is defined as the OVP Threshold Voltage that triggers OVP protection function. The OVP Threshold Voltage is the VREQ voltage plus the OVPTHR offset voltage (mV). The default value for the OVPTHR is 19h (2000mV) and the LSB is 80mV. Please refer to the “Overvoltage Protection” section for more details.

OVPTHR	Bit	Attribute	Pwr-on	Description
OVPTHR	7:0	RW	19h	The OVP Threshold Voltage is the VREQ voltage plus OVPTHR offset voltage (mV); the LSB is 80mV. The default value is 19h (2000mV), which means the OVP Threshold Voltage is $V_{VREQ} + 2000\text{mV}$ by default.

### OCPTHR

The OCPTHR register is defined as the OCP Threshold Current that triggers OCP protection function. The OCP Threshold Current is 110% of the OCPTHR current value. The default value for the OCPTHR is 00h and the LSB is 50mA.

If the OCPTHR is set to 0, the OCP Threshold Current will be updated to 110% of the selected PDO maximum current after successful negotiation with the PD source. Please refer to the “Overcurrent Protection” section for more details.

OCPTHR	Bit	Attribute	Pwr-on	Description
OCPTHR	7:0	RW	00h	The OCP Threshold Current is 110% of the OCPTHR current value; the LSB is 50mA. The default value is 00h, which means the OCP Threshold Current will be updated to 110% of the selected PDO maximum current after successful negotiation.

### OTPTHR

The OTPTHR register is defined as the OTP Threshold Temperature (°C) that triggers OTP protection function. The default value for the OTPTHR is 78h (120°C). Please refer to the “Overtemperature Protection and De-Rating” section for more details.

OTPTHR	Bit	Attribute	Pwr-on	Description
OTPTHR	7:0	RW	78h	OTP Threshold Temperature (unit: °C) The temperature threshold triggers OTP function; the default value for OTPTHR is 78h (120°C).

### DRTHR

The DRTHR register is defined as the De-Rating Threshold Temperature (°C) that triggers the De-Rating function. The default value for the DRTHR is 78h (120°C). Please refer to the “Overtemperature Protection and De-Rating” section for more details.

DRTHR	Bit	Attribute	Pwr-on	Description
DRTHR	7:0	RW	78h	De-Rating Threshold Temperature (unit: °C) The temperature threshold triggers De-Rating function; the default value for DRTHR is 78h (120°C).

### SRC PDO

The SRC PDO register can obtain all of the PD Source Power Capabilities and has a total length of 28 bytes.

SRC PDO	Byte	Attribute	Pwr-on	Description
SRC_EPR_PDO13	25:24	RO	0000h	For data format, refer to <b>SRC_EPR_PDO8 ~ SRC_EPR_PDO13</b>
SRC_EPR_PDO12	23:22	RO	0000h	
SRC_EPR_PDO11	21:20	RO	0000h	
SRC_EPR_PDO10	19:18	RO	0000h	
SRC_EPR_PDO9	17:16	RO	0000h	
SRC_EPR_PDO8	15:14	RO	0000h	
SRC_SPR_PDO7	13:12	RO	0000h	For data format, refer to <b>SRC_SPR_PDO1 ~ SRC_SPR_PDO7</b>
SRC_SPR_PDO6	11:10	RO	0000h	
SRC_SPR_PDO5	9:8	RO	0000h	
SRC_SPR_PDO4	7:6	RO	0000h	
SRC_SPR_PDO3	5:4	RO	0000h	
SRC_SPR_PDO2	3:2	RO	0000h	
SRC_SPR_PDO1	1:0	RO	0000h	

## SRC\_SPR\_PDO1 ~ SRC\_SPR\_PDO7

The SRC\_SPR\_PDO register can obtain the PD Source SPR PDO of a specific index; each length is 2 bytes. The structure of the SRC\_SPR\_PDO register is as follows:

SRC_SPR_PDO	Bit	Attribute	Pwr-on	Description	
DETECT	15	RO	0h	0: Not detected 1: Detected	
TYPE	14	RO	0h	0: Fixed PDO 1: PPS APDO	
CURRENT_MAX	13:10	RO	0h	0: 0.00A ~ 1.24A (Less than 1.24A) 1: 1.25A ~ 1.49A 2: 1.50A ~ 1.74A 3: 1.75A ~ 1.99A 4: 2.00A ~ 2.24A 5: 2.25A ~ 2.49A 6: 2.50A ~ 2.74A 7: 2.75A ~ 2.99A 8: 3.00A ~ 3.24A 9: 3.25A ~ 3.49A 10: 3.50A ~ 3.74A 11: 3.75A ~ 3.99A 12: 4.00A ~ 4.24A 13: 4.25A ~ 4.49A 14: 4.50A ~ 4.99A 15: 5.00A ~ (More than 5.00A)	
PEAK_CURRENT or VOLTAGE_MIN	9:8	RO	0h	PEAK_CURRENT	VOLTAGE_MIN
				For Fixed PDO (bit[14]=0) Peak Current	For PPS APDO (bit[14]=1) 0 : Reserved 1 : 3.3V 2 : 3.3V < VOLTAGE_MIN ≤ 5V 3 : others
VOLTAGE_MAX	7:0	RO	0h	If bit[14]=0 (Fixed PDO) : Voltage in 100mV units If bit[14]=1 (PPS APDO) : Maximum Voltage in 100mV units	

## SRC\_EPR\_PDO8 ~ SRC\_EPR\_PDO13

The SRC\_EPR\_PDO register can obtain the PD Source EPR PDO of a specific index; each length is 2 bytes. The structure of the SRC\_EPR\_PDO register is as follows:

SRC_EPR_PDO	Bit	Attribute	Pwr-on	Description	
DETECT	15	RO	0h	0: Not detected 1: Detected	
TYPE	14	RO	0h	0: Fixed PDO 1: AVS APDO	
CURRENT_MAX	13:10	RO	0h	0: 0.00A ~ 1.24A (Less than 1.24A) 1: 1.25A ~ 1.49A 2: 1.50A ~ 1.74A 3: 1.75A ~ 1.99A 4: 2.00A ~ 2.24A 5: 2.25A ~ 2.49A 6: 2.50A ~ 2.74A 7: 2.75A ~ 2.99A 8: 3.00A ~ 3.24A 9: 3.25A ~ 3.49A 10: 3.50A ~ 3.74A 11: 3.75A ~ 3.99A 12: 4.00A ~ 4.24A 13: 4.25A ~ 4.49A 14: 4.50A ~ 4.99A 15: 5.00A ~ (More than 5.00A)	
PEAK_CURRENT or VOLTAGE_MIN	9:8	RO	0h	PEAK_CURRENT	VOLTAGE_MIN
				For Fixed PDO (bit[14]=0) Peak Current	For AVS APDO (bit[14]=1) 0 : Reserved 1 : 15V 2 : 15V < VOLTAGE_MIN ≤ 20V 3 : others
VOLTAGE_MAX	7:0	RO	0h	If bit[14]=0 (Fixed PDO) : Voltage in 200mV units If bit[14]=1 (AVS APDO) : Maximum Voltage in 200mV units	

Bits 9...8	Description for PEAK_CURRENT
00	Peak current equals $I_{OC}$ (default) or look at extended Source capabilities
01	Overload Capabilities: 1. Peak current equals 150% $I_{OC}$ for 1ms @ 5% duty cycle (low current equals 97% $I_{OC}$ for 19ms) 2. Peak current equals 125% $I_{OC}$ for 2ms @ 10% duty cycle (low current equals 97% $I_{OC}$ for 18ms) 3. Peak current equals 110% $I_{OC}$ for 10ms @ 50% duty cycle (low current equals 90% $I_{OC}$ for 10ms)
10	Overload Capabilities: 1. Peak current equals 200% $I_{OC}$ for 1ms @ 5% duty cycle (low current equals 95% $I_{OC}$ for 19ms) 2. Peak current equals 150% $I_{OC}$ for 2ms @ 10% duty cycle (low current equals 94% $I_{OC}$ for 18ms) 3. Peak current equals 125% $I_{OC}$ for 10ms @ 50% duty cycle (low current equals 75% $I_{OC}$ for 10ms)
11	Overload Capabilities: 1. Peak current equals 200% $I_{OC}$ for 1ms @ 5% duty cycle (low current equals 95% $I_{OC}$ for 19ms) 2. Peak current equals 175% $I_{OC}$ for 2ms @ 10% duty cycle (low current equals 92% $I_{OC}$ for 18ms) 3. Peak current equals 150% $I_{OC}$ for 10ms @ 50% duty cycle (low current equals 50% $I_{OC}$ for 10ms)

loc: The Operating Current of an RDO (The Operating Current Select parameter of PD\_REQMSG)  
For more information, refer to the "Peak Current" section of the USB PD Specification.

## PD\_REQMSG

The PD\_REQMSG register is defined as the request message format to initiate negotiation with the PD source. The request message can select the source PDO index and request the desired voltage and current output. If the selected PDO is a Fixed PDO (TYPE=0), setting the VOLTAGE\_SEL has no meaning (except in VOLTAGE\_SEL=FFh).

PD_REQMSG	Bit	Attribute	Pwr-on	Description
PDO_INDEX	15:12	WO	0h	Source PDO index select [1] ~ [7]: For SRC_SPR_PDO1 ~ SRC_SPR_PDO7 selection, if its corresponding PDO is detected [8] ~ [13]: For SRC_EPR_PDO8 ~ SRC_EPR_PDO13 selection, if its corresponding PDO is detected Others: Reserved, Shall Not be used
CURRENT_SEL	8:11	WO	0h	Operating Current Select 0: 1.00A 1: 1.25A 2: 1.50A 3: 1.75A 4: 2.00A 5: 2.25A 6: 2.50A 7: 2.75A 8: 3.00A 9: 3.25A 10: 3.50A 11: 3.75A 12: 4.00A 13: 4.25A 14: 4.50A 15: 5.00A or Maximum Current <sup>(Note1)</sup>
VOLTAGE_SEL	7:0	WO	0h	Output Voltage Select If select SRC_SPR_PDO (PDO1 ~ PDO7): <sup>(Note2)</sup> Output Voltage in 100mV units for SPR PPS APDO selected If select SRC_EPR_PDO (PDO8 ~ PDO13): Output Voltage in 200mV units for EPR AVS APDO selected FFh: Maximum Voltage <sup>(Note1)</sup>
Note1: If set CURRENT_SEL=Fh and VOLTAGE_SEL=FFh, AP33772S will request the Maximum Current and Maximum Voltage of the selected Source PDO				
Note2: Setting VOLTAGE_SEL has no meaning when a Fixed PDO is selected				

The AP33772S provides a special request message to request the maximum current and maximum voltage of the selected source PDO by setting only PDO\_INDEX and keeping CURRENT\_SEL = Fh and VOLTAGE\_SEL = FFh.

For example, if source PDO3 is detected, the AP33772S will write PD\_REQMSG=3FFFh to request the maximum current and maximum voltage of source PDO3.

PD_REQMSG	Bit	Attribute	Pwr-on	Value
PDO_INDEX	15:12	WO	0h	1 to 13
CURRENT_SEL	8:11	WO	0h	Fh
VOLTAGE_SEL	7:0	WO	0h	FFh

## PD\_CMDSMSG

The PD\_CMDSMSG register is defined as the command message that issues the specific USB PD command.

AP33772S	AP33772S	AP33772S	AP33772S	AP33772S
-	7:4	WO	0h	Reserved
-	3	WO	0h	Reserved
-	2	WO	0h	Reserved
-	1	WO	0h	Reserved
HRST	0	WO	0h	1: Issue Hard Reset command

## PD\_MSGRLT

The PD\_MSGRLT register is defined as the message processing results of PD\_REQMSG and PD\_CMDMSG.

The RESPONSE parameter displays the message response made by the AP33772S, based on the interaction result with the PD source. The response values and meanings are as follows:

PD_MSGRLT	Bit	Attribute	Pwr-on	Description
-	7:4	RO	0h	Reserved
-	3	RO	0h	Reserved
RESPONSE	2:0	RO	0h	The message response 0: System busy or no response 1: Success 2: Invalid command or argument 3: Command not supported or rejected 4: Transaction failed. No GoodCRC is received after sending Others: Reserved

## Chapter 6. Function Description

### 6.1 I2C Request Message

The I2C request message (PD\_REQMSG) can update the PDO index, Operating Current, and Output Voltage settings during runtime.

- PDO\_INDEX assigns the source PDO index.
- CURRENT\_SEL sets the Operating Current value of RDO.
- VOLTAGE\_SEL sets the Output Voltage value of PPS/AVS RDO, but has no effect for selecting Fixed PDO.

The AP33772S starts to negotiate with the PD source after receiving the PD\_REQMSG. When the PD negotiation completes, the AP33772S sets the STATUS.READY bit and updates the negotiation result in the PD\_MSGRLT.RESPONSE.

### 6.2 Support EPR / AVS

After the first negotiation with the PD source, which supports EPR Mode, the AP33772S will try to enter EPR Mode when PDCONFIG.EPR\_MODE is set to 1. If the AP33772S successfully enters EPR Mode, the device stores the EPR Source Capability in the SRC\_EPR\_PDOx registers and enables the EPR request.

### 6.3 VOUT MOS Switch

When the VREQ voltage is more than or equal to the VSELMIN voltage, the AP33772S enables the associated MOS switches and then VBUS is connected to VOUT.

When overvoltage, undervoltage, overcurrent, or overtemperature protection occurs, the associated VOUT MOS switches are turned off to protect the electrical appliances from possible damage. The host MCU will need to load a new PD\_REQMSG to start the PD negotiation process, resuming quick-charging operation.

By default, the VOUT MOS switches are controlled by the AP33772S. Writing the VOUTCTL parameter of the SYSTEM register can force the VOUT MOS switches to turn OFF/ON.

## 6.4 LED Indication

The AP33772S controls LED lighting through the LED pin. The table below summarizes the LED indication and VOUT in each State.

State	LED Indication	VOUT	Comments
<b>INIT</b>	N/A	OFF	VBUS/Rp attached and AP33772S initialization
<b>CHARGING</b>	4-sec Breathing	ON	Successful negotiation or entering of Non-PD Mode; charging start
<b>MISMATCH</b>	Full Light	OFF	VSELMIN mismatch ( $V_{VREQ} < V_{VSELMIN}$ )
<b>MOISTURE</b>	2-sec Flicker	OFF	DN abnormal impedance detected
<b>FAULT</b>	0.6-sec Flicker	OFF	OVP, OCP, UVP, or OTP occurs

## 6.5 Interrupt

The AP33772S supports a level-triggered interrupt signal through the INT pin to the host MCU. The MASK register defines the enable and disable options of ON and OFF for each interruptible event.

Interrupt initialization is required before use. When an interruptible event occurs, the AP33772S will set the INT level high (1) if the relevant event of the MASK register is enabled. Then the host MCU should read STATUS to obtain the status of the AP33772S in real time.

For example, if the OVP\_MSK is set to 1 (MASK = 0x13), INT is to be set high when an OVP event occurs.

## 6.6 CC Flip Indication

The AP33772S uses the FLIP Pin for CC Flip Indication. If CC is non-flipped (CC1 attached), the FLIP output is low. If CC is flipped (CC2 attached), the FLIP output is high.

CC Flip Indication		
CC Detection	CC1 Attached	CC2 Attached
FLIP Output	Low (0)	High (1)

## 6.7 Legacy Type A Charger with Type A-to-C Cable

When the energy source is from a legacy Type A charger, with a Type A-to-C cable connection to the Type-C Connector-equipped devices (TCD), the AP33772S enters Non-PD Mode after PD negotiation fails. When the VREQ voltage is less than the VSELMIN voltage, the associated VOUT MOS switches are turned off. The table below shows the Non-PD Mode state of the AP33772S.

Non-PD Mode State		
$V_{VREQ}$	$V_{VSELMIN}$	$V_{VOUT}$
$V_{VREQ} = 5V$	$V_{VSELMIN} = 5V$	ON
$V_{VREQ} = 5V$	$V_{VSELMIN} > 5V$	OFF

## 6.8 Temperate Estimate

The AP33772S measures and estimates the temperature value based on four User-Entered NTC resistance values vs. temperature (TR25, TR50, TR75, and TR100) in the TCD's practical-usage temperature range.

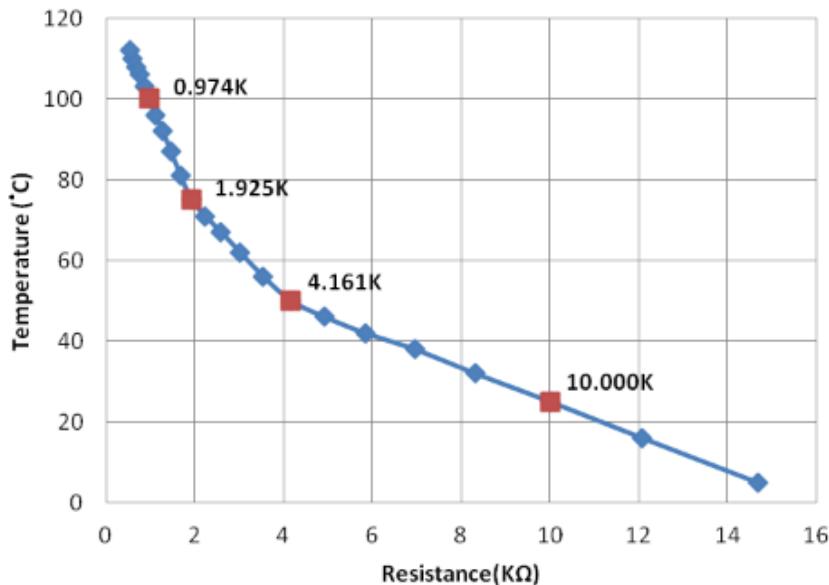
The AP33772S use Murata NTC NCP03XH103 by default. The table below shows the NTC resistance values vs. temperature.

Register	Default Value	NTC Resistance (KΩ)	Temperature (°C)
TR25	2710h	10	25
TR50	1041h	4.161	50
TR75	0788h	1.928	75
TR100	03CEh	0.974	100

If the calculated NTC resistance value is bounded by TR25 and TR100, the AP33772S uses the "LINEAR INTERPOLATION" of the two bounding TR values to estimate the temperature value, and deposits this estimated temperature value in the I2C register TEMP.

If the calculated NTC resistance value is higher than TR25 value, the AP33772S uses the "LINEAR EXTRAPOLATION" of TR50 and TR25 to estimate the temperature below 25°C. Similarly, if the calculated resistance value is lower than TR100 value, the AP33772S uses the "LINEAR EXTRAPOLATION" of TR75 and TR100 to estimate the temperature above 100°C.

**Calculated Resistance vs. Estimated Temperature**



Ex. The AP33772S calculates that the resistance value of NTC is 2.250kΩ. The near-boundary 50°C is 4.161kΩ; 75°C is 1.925kΩ. Therefore, 2.250kΩ corresponds to:

$$\text{SLOPE} = (1.925\text{k}\Omega - 4.161\text{k}\Omega) / (75^\circ\text{C} - 50^\circ\text{C}) = -0.08944 \text{ k}\Omega/\text{C}$$

$$\text{Temperature} = 50^\circ\text{C} + (2.250\text{k}\Omega - 4.161\text{k}\Omega) / (-0.08944 \text{ k}\Omega/\text{C}) = 71.4^\circ\text{C}$$

So, the TEMP register value is to be set at 47h (71°C).

## Chapter 7. Protection

### 7.1 Overvoltage Protection (OVP)

The AP33772S triggers OVP protection when the VBUS voltage is higher than the OVP Threshold Voltage. The table below summarizes the correspondence between VREQ, OVPTHR, and OVP Threshold Voltage.

Mode	Criteria	OVP Threshold Voltage
SPR Mode	$(V_{VREQ} + V_{OVPTHR}) \leq 20V$	$V_{VREQ} + V_{OVPTHR}$
	$(V_{VREQ} + V_{OVPTHR}) > 20V$	$V_{VREQ} * 110\%$
EPR Mode	$(V_{VREQ} + V_{OVPTHR}) \leq 40V$	$V_{VREQ} + V_{OVPTHR}$
	$(V_{VREQ} + V_{OVPTHR}) > 40V$	$V_{VREQ} * 110\%$

The OVP debounce time mechanism is to prevent false triggering caused by various spurious noises. The OVP debounce time is preset to 30ms. If the VBUS voltage is greater than the OVP threshold voltage after the debounce time (30ms), the STATUS.OVP will be set to 1 and the associated VOUT MOS switches are turned off. The host MCU will need to load a new PD\_CMDMSG to start the PD negotiation process, resuming quick-charging operation.

### 7.2 Overcurrent Protection (OCP)

The AP33772S triggers OCP protection when the charging current is larger than OCP Threshold Current. The table below shows the correspondence between OCPTHR and OCP Threshold Current. The default value of the OCPTHR register is 00h.

If the OCPTHR value is still 00h after successful negotiation with the PD source, the OCP Threshold Current should be updated to 110% of the maximum current ( $I_{MAX}$ ) of the selected PDO/APDO.

If the OCPTHR value has been updated through I2C interface, the OCP Threshold Current should be updated to 110% of the OCPTHR value.

OCPTHR	OCP Threshold Current
OCPTHR = 0	$I_{MAX} * 110\%$ (Note)
OCPTHR != 0	$I_{OCPTHR} * 110\%$

Note:  $I_{MAX}$ : The Maximum Current of PDO/APDO

The default OCP debounce time is 30ms. If the charging current is larger than OCP Threshold Current after debounce time (30ms), the STATUS.OCP will be set to 1 and the associated VOUT MOS switches are turned off. The host MCU will need to load a new PD\_CMDMSG to start the PD negotiation process, resuming quick-charging operation.

### 7.3 Undervoltage Protection (UVP)

The AP33772S triggers UVP protection when VBUS voltage is lower than UVP Threshold Voltage. The table below shows the correspondence between UVPTHR and UVP Threshold Voltage.

The default value of the Undervoltage Protection Threshold (UVPTHR) is 80%, which can be modified by writing the UVPTHR command.

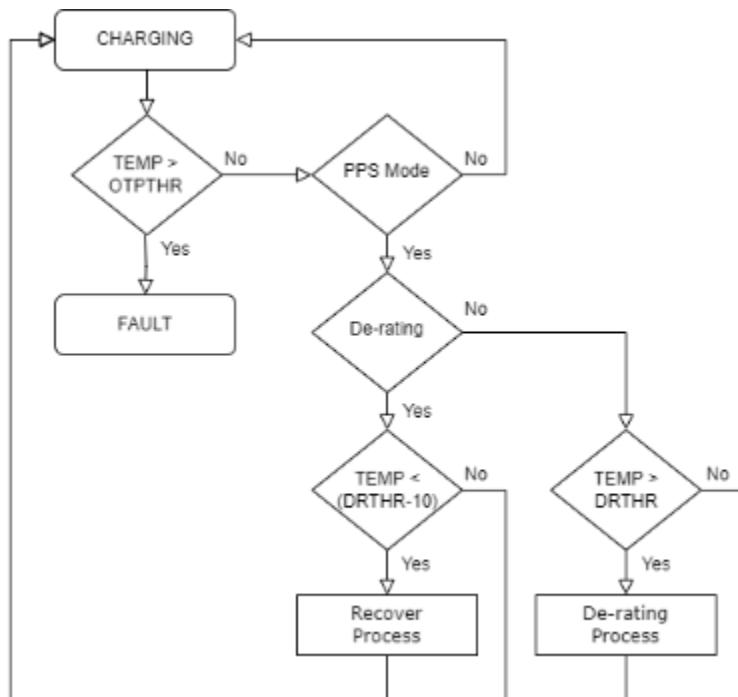
UVPTHR	UVP Threshold Voltage
1	$V_{VREQ} * 80\%$
2	$V_{VREQ} * 75\%$
3	$V_{VREQ} * 70\%$

The default UVP debounce time is 30ms. If VBUS voltage is lower than UVP Threshold Voltage after debounce time (30ms), the STATUS.UVP will be set to 1 and the associated VOUT MOS switches are turned off. The host MCU will need to load a new PD\_CMDMSG to start the PD negotiation process, resuming quick-charging operation.

## 7.4 Overtemperature Protection (OTP) and De-Rating

The host MCU can access the estimated temperature of a potential hot spot by accessing the TEMP register. A NTC thermistor is used to connect to the OTP pin and ground nearby the potential hot spot. The host MCU must initialize the TR25, TR50, TR75, and TR100 registers before reading the TEMP register or enabling OTP and power de-rating functions.

The default value of the OTPTHR register is 78h (120°C), which can be updated through the I2C interface. If the TEMP value rises over the OTPTHR value after the de-bouncing time (30ms), the STATUS.OTP will be set to 1 and the associated VOUT MOS switches are turned off. The host MCU will need to load a new PD\_CMDMSG to start the PD negotiation process, resuming quick-charging operation.



Furthermore, the AP33772S defines the DRTHR register as the threshold temperature value to trigger the power de-rating functions. If the requested source PDO is PPS APDO, and when the TEMP value rises over the DRTHR value after de-bouncing time (30ms), the input current will be reduced by 50% through sending out a new RDO to negotiate with the PD source device.

The AP33772S continuously monitors the temperature at the potential hot spot. After a time duration, if the TEMP value under the DRTHR value is more than 10°C, the device will recover charging power.

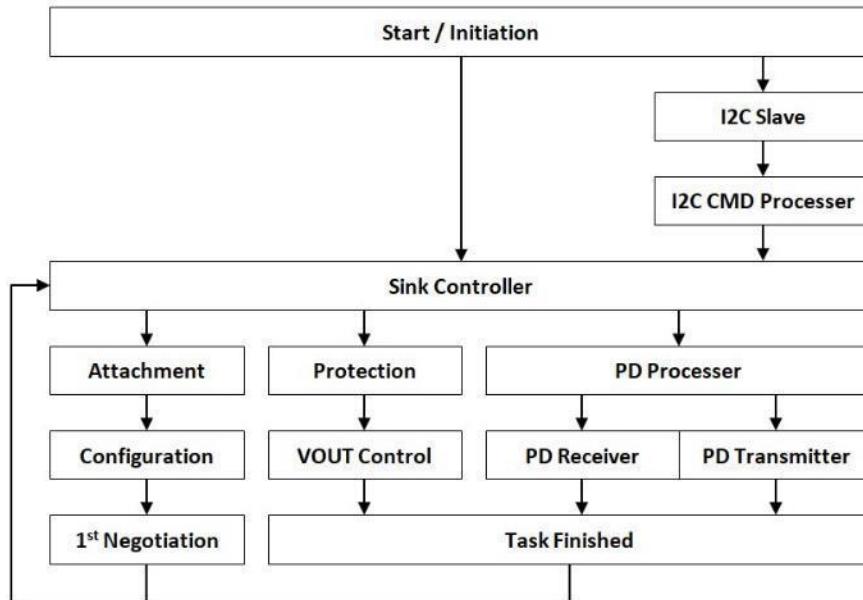
## 7.5 Moisture Detection

After connecting to the Power Source, the AP33772S will first check whether the impedance of the DN pin is abnormal. If the DN impedance check fails, the AP33772S goes into the MOISTURE state and does not acknowledge the Source Capability Messages.

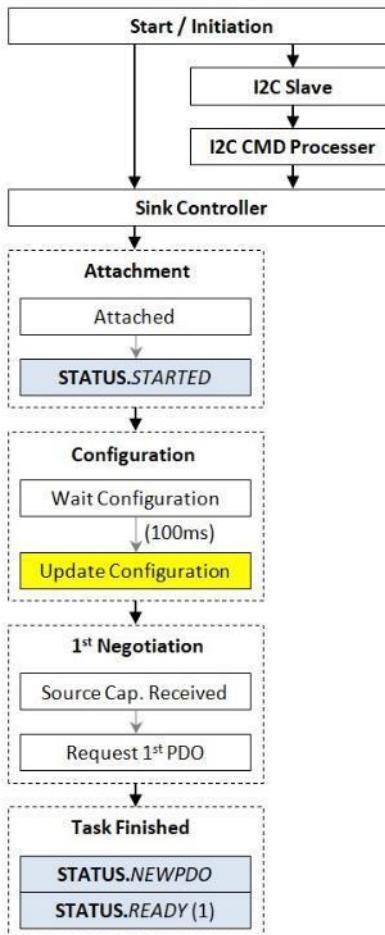
In the MOISTURE state, the associated VOUT MOS switches are turned off with the LED flickering in the “MOISTURE” pattern. The AP33772S will check the DN impedance over 2200ms. If the DN pin impedance check is normal, the AP33772S will start to negotiate with the source.

## Chapter 8. Firmware Flow

### 8.1 Firmware Block Diagram



## 8.2 Firmware Startup Process



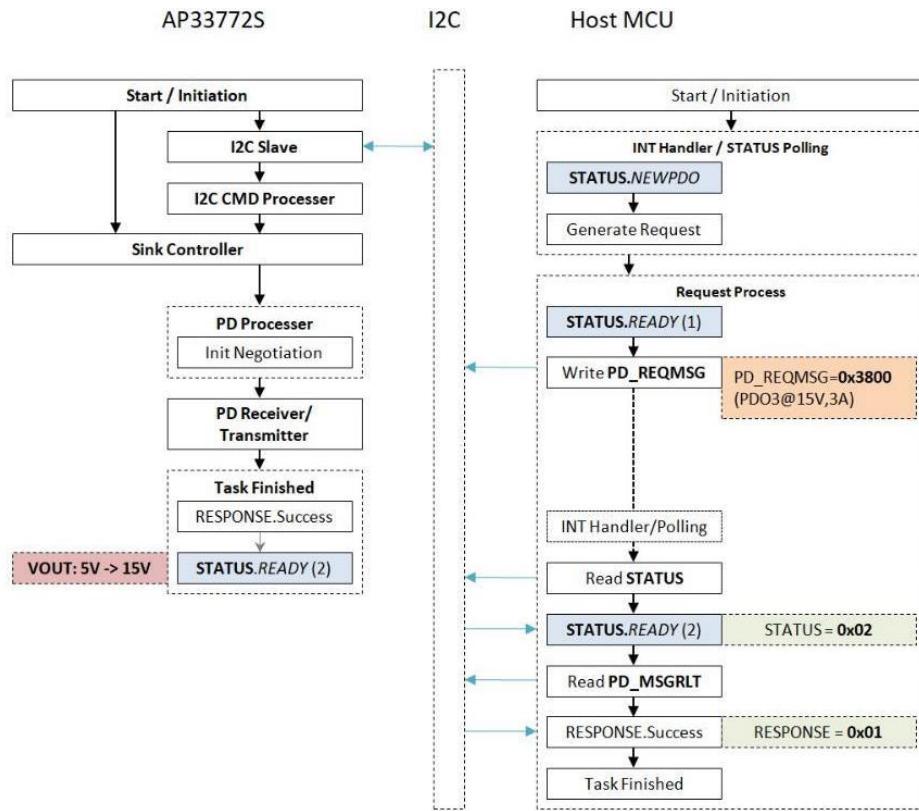
After the AP33772S is powered on, the firmware begins to initialize the sink controller and I2C slave state machine. When the sink controller detects that the VBUS and Rp are attached, the STATUS.STARTED flag is set to 1 and the interrupt signal is triggered through INT pin to the host MCU.

Once the AP33772S is started (STATUS.STARTED = 1), the host MCU can disable/enable specific modules based on the TCD requirements by writing the configurable registers. Then 100ms after the AP33772S starts, the initial configuration is updated accordingly and the 1st negotiation with the PD source begins.

After the 1st negotiation is completed, the source capabilities are stored in the SRC\_SPR\_PDO registers. If the PD source supports EPR mode, the EPR source capabilities are stored in the SRC\_EPR\_PDO registers. Then the STATUS.NEW PDO flag is set to 1, indicating that the new source capabilities have been received. The host MCU should read the SRC PDO register and generate a request message (PD\_REQMSG) based on the TCD requirements.

Finally, the STATUS.READY flag is set to 1, indicating that the startup process is completed and the host MCU can send requests thereafter.

## 8.3 Request Process



For example, on the energy-sourcing side, the system uses a USB PD3.1 compliance charger (PDC) rated at 60W output power (5V/9V/15V/20V@3A). For the energy-sinking side, a battery-powered Type-C mobile device adopts the AP33772S as the USB PD3.1 Sink compliance controller. The host appliance requests 45W power at 15V@3A input and starts charging after successful negotiation.

Based on the TCD requirements and the source capabilities obtained by reading the SRCPDO register, the host MCU selects the required PDO\_INDEX, CURRENT\_SEL, and VOLTAGE\_SEL to generate the request message (PD\_REQMSG).

After the AP33772S startup process is completed (STATUS.READY=1), the host MCU can initiate the request process through the I2C interface. Here, PD\_REQMSG is written to 3800h to request 45W power at 15V@3A. The request parameters are described in the following table.

PD_REQMSG	Bit	Attribute	Value	Description
PDO_INDEX	15:12	WO	3h	Select source PDO index "3"
CURRENT_SEL	8:11	WO	8h	Select Operating Current @3.00A
VOLTAGE_SEL	7:0	WO	0h	For fixed PDO selection, this parameter remains at 0

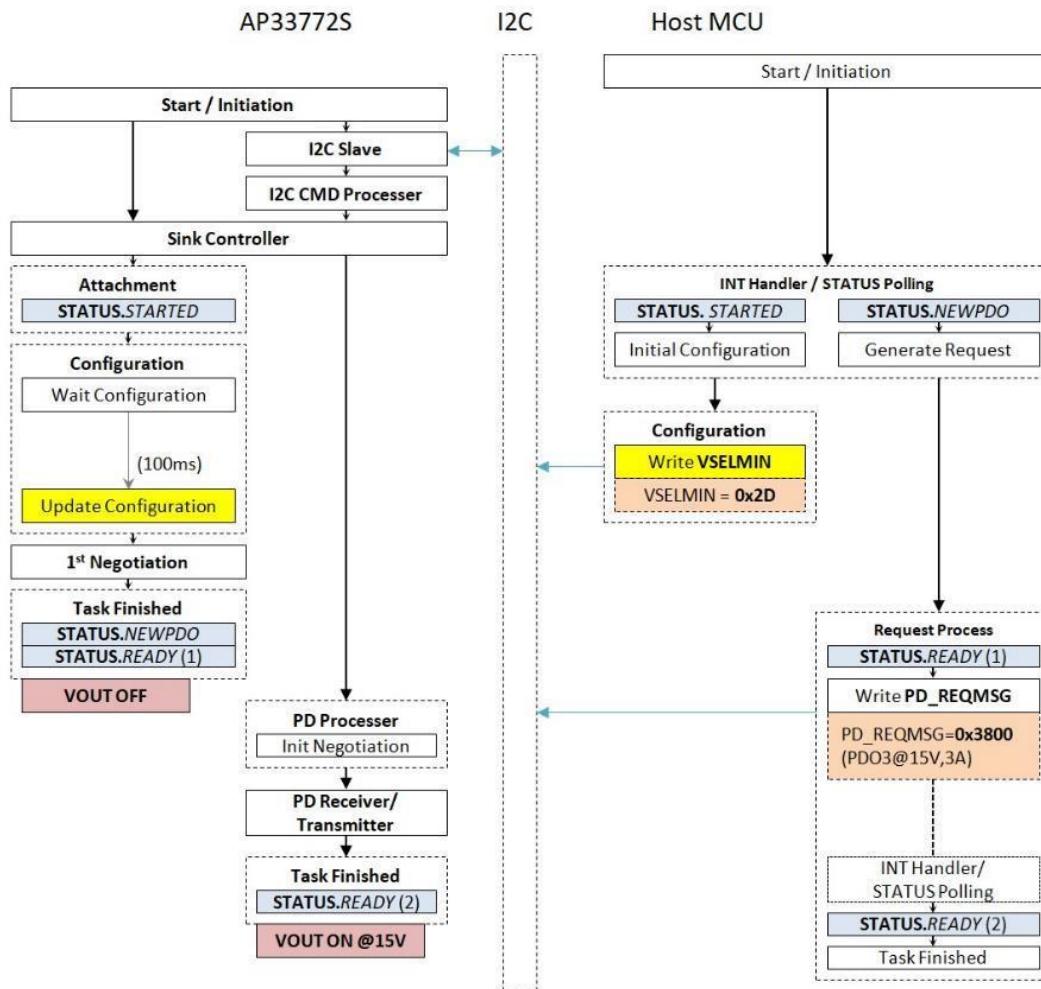
When receiving the PD\_REQMSG command, the AP33772S will initiate negotiation with the PD source according to the requirements of the host MCU. After the PD negotiation is completed, and if the AP33772S receives a PS\_RDY message from the PD source, the device sets the PD\_MSGRLT.RESPONSE parameter to 1 (Success). Then, the VOUT voltage transitions from 5V to 15V.

Finally, the STATUS.READY flag is set to 1, indicating that the request process is completed and the host MCU can send other requests/commands thereafter.

Therefore, the host MCU should handle the INT signal or poll STATUS to obtain the status of the AP33772S in real time.

1. STARTED = 1, the host MCU can disable/enable specific modules by writing MASK, CONFIG, PDCONFIG, and VSELMIN registers at startup.
2. NEW PDO = 1, the host MCU should read the SRCPDO register to obtain the latest PD source capabilities, and then search for the appropriate PDO again.
3. READY = 1, the host MCU can send requests/commands or read/write any register through the I2C interface.
4. After writing to the PD\_REQMSG register, the host MCU should wait for the STATUS.READY flag to be set high and then read the PD\_MSGRLT register to obtain the negotiation result.

## 8.4 Initial Configuration



Continuing the example from the previous section, the battery-powered host appliance requires the VOUT voltage to be higher than 9V to protect the circuit, and requests 45W power at 15V@3A for charging.

The power-on value of the VSELMIN is 19h (5000mV). Under the default configuration, if the VREQ voltage is more than or equal to 5000mV, the AP33772S enables the VOUT MOS switches. During the 1<sup>st</sup> negotiation, the AP33772S requests the default PDO1@5V and the VREQ voltage is set to 5V. Since VREQ voltage is equal to VSELMIN voltage, the VOUT MOS switches turn “ON” and then the VBUS is connected to VOUT. Therefore, the default output of the AP33772S is 5V when connected to the PD source, which may damage this host appliance.

Once the AP33772S is started (STARTED=1), the host MCU can change the power-on values of the configurable registers and the initial configurations will be updated accordingly after 100ms. For this custom application, the host MCU sets VSELMIN to 2Dh (9000mV) during configuration. After the 1<sup>st</sup> negotiation is completed, the VOUT MOS switches are turned “OFF” since VREQ voltage (5V) is less than VSELMIN voltage (9V).

Then the host MCU writes PD\_REQMSG to 3800h to request 45W power at 15V@3A. After successful negotiation, the VOUT MOS switches are turned “ON” since VREQ voltage (15V) is more than VSELMIN voltage (9V). By modifying the initial configuration, the host appliance can ensure that VOUT voltage is always greater than 9V.

## Chapter 9. Compliance test

### Product Testing Information

- Product Name: AP33772S
- Model: CY33772S
- USB-IF TID: 10062

 <b>Power Delivery</b> <b>Compliance Test Report</b>	
October 11, 2023 Revision 1.1	
<b>GRL Project Number</b>	CYN-TP-09192301
Canyon Semiconductor	
<b>Customer</b>	Joseph Liang <a href="mailto:josephliang@canyon-semi.com.tw">josephliang@canyon-semi.com.tw</a> 03-5797868
<b>Test Location</b>	Granite River Labs – Taipei
<b>Product Market Name</b>	AP33772S
<b>Model/Part Number</b>	CY33772S
<b>Product Description</b>	PD 3.1 EPR PD Controller
<b>Product Type</b>	USB Type-C Consumer
<b>PPD in Watts</b>	140W
<b>FW Version</b>	CYF24D0_K2xxn113
<b>USB-IF TID</b>	10062
<b>VID<sub>ls</sub></b>	2A41
<b>PID<sub>ls</sub></b>	2570
<b>Scope of Testing</b>	PD 3.1 Compliance Tests
<b>Test Results</b>	<b>PASS</b>
<b>GRL Test Engineer</b>	
<b>GRL Reviewer</b>	
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**Chapter 10. Revision History**

Revision	Hardware Version	Firmware Version	Change Description	Date
1	1.0	1.0	First release	11/16/2023
2	1.0	1.1	Remove VDC	05/03/2024

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